

# EL.BO. Service

## Electronic packaging

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### Buried Metal Product Specifications

#### ELS-707

Static Shielding Material  
Complies with EN 61340-5-1  
and ANSI/ESD S20.20

#### Construction:

Anti-Static
<b>Polyester</b>
Metal
<b>Polyethylene</b>
Anti-Static

<u>Physical Properties</u>	<u>Test method</u>	<u>Specifications</u>
Thickness	LAB # 001	3.0 mil ± 10%
Puncture Resistance	FTMS 101C method 2065	12 lbs
Yield	LAB # 002	9,000 sqin/lb
Tensile Strength	ASTM D-882-67	MD > 16 lbs / in TD > 15 lbs / in
Mullen Burst	ASTM D-774	100 psi
Seal Strength	ASTM f88-94	> 12 lbs / in
Play Bond	ASTM D-1876-95	MD > 2.0 lbs.p / in TD > 2.5 lbs.p / in
Optical Density		0.35 – 0.45
Tear Initiation	ASTM D -1004	MD > .95 lbs.p / mil TD > .90 lbs.p / mil
MVTR	ASTM F-1249	0.35 gms nominal
Haze	ASTM D-1003	4%
Transparency	ASTM D-1003	40%
Heat Seal		375°F 0.5 sec. 60 psi
Blocking		None

<u>Electrical Properties</u>	<u>Test Method</u>	<u>Specifications</u>
Surface Resistance	IEC 61340-2-3 at 15 % RH	PE < 10 <sup>11</sup> Ohm PET < 10 <sup>11</sup> Ohm
Electrostatic Decay	FTMS 101 method 4046	< 2 sec.
Capacitance Probe	EIA-541	< 30 volts difference
Metal Layer	ETS-803 at 15 % RH	< 100 Ohm
Electrostatic shielding	Energy test EN 61340-5-1	< 50 n J

<u>Chemical Properties</u>	<u>Test Method</u>	<u>Specifications</u>
Contact Corrosivity	FTMS 101C method 3005	no visible sign after testing of deterioration
Ion Content	(Sodium, Fluoride, Phosphate, & Sulfate Ions)	Below Detectable Levels
Amines & Amide Free		

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